

	Type	Hits	Search Text	DBs
1	BRS	3898	install\$5 same (docking or pedestal)	USPAT; EPO; JPO; DERWENT
2	BRS	871	(install\$5 same (docking or pedestal)) and machin\$4	USPAT; EPO; JPO; DERWENT
3	BRS	179	((install\$5 same (docking or pedestal)) and machin\$4) and platform	USPAT; EPO; JPO; DERWENT
4	IS&R	298	(248/678).CCLS.	USPAT; EPO; JPO; DERWENT
5	BRS	1	schauer-ronald-\$.in.	USPAT; EPO; JPO; DERWENT
6	BRS	191	davies-john-\$.in.	USPAT; EPO; JPO; DERWENT
7	BRS	1	davies-john-charles.in.	USPAT; EPO; JPO; DERWENT
8	BRS	3119	wafer adj fabricat\$3	USPAT; EPO; JPO; DERWENT
9	BRS	1271	(wafer adj fabricat\$3) and (machine or machinery or equipment)	USPAT; EPO; JPO; DERWENT
10	BRS	1011	((wafer adj fabricat\$3) and (machine or machinery or equipment)) and manufactur\$4	USPAT; EPO; JPO; DERWENT
11	BRS	0	"semiconductor equipment manufacturing institute"	USPAT; EPO; JPO; DERWENT
12	BRS	364692	"SEMI"	USPAT; EPO; JPO; DERWENT
13	BRS	162	((((wafer adj fabricat\$3) and (machine or machinery or equipment)) and manufactur\$4) and "SEMI"	USPAT; EPO; JPO; DERWENT

	Type	Hits	Search Text	DBs
16	BRS	6218	applied adj materials.as.	USPAT; EPO; JPO; DERWENT
17	BRS	3244	(applied adj materials.as.) and wafer	USPAT; EPO; JPO; DERWENT
18	BRS	813	((applied adj materials.as.) and wafer) and pedestal	USPAT; EPO; JPO; DERWENT
19	BRS	442	((((applied adj materials.as.) and wafer) and pedestal) and (pedestal same support))	USPAT; EPO; JPO; DERWENT
20	BRS	81	(((((applied adj materials.as.) and wafer) and pedestal) and (pedestal same support))) and (machine or machinery)	USPAT; EPO; JPO; DERWENT
21	BRS	166612	method\$2 and installation	USPAT; EPO; JPO; DERWENT
22	BRS	64467	(method\$2 and installation) and (machine or machinery or equipment)	USPAT; EPO; JPO; DERWENT
23	BRS	117059	52/\$.ccls.	USPAT; EPO; JPO; DERWENT
24	BRS	2263	((method\$2 and installation) and (machine or machinery or equipment)) and 52/\$.ccls.	USPAT; US-PGPUB